

Product End-of-Life Disassembly Instructions
Product
Category: **Networking**
Marketing Name / Model

[List multiple models if applicable.]

Name / Model #1 Aruba 7210 (RW) Controller

Name / Model #2 Aruba 7210 (US) Controller

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by Directive 2012/19/EU of the European Parliament and of the Council on Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	
Cathode Ray Tubes (CRT)		
Capacitors / condensers (Containing PCB/PCT)		
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		
External electrical cables and cords		
Gas Discharge Lamps		
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		

Item Description	Notes	Quantity of items included in product
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	
Components and waste containing asbestos		
Components, parts and materials containing refractory ceramic fibers		
Components, parts and materials containing radioactive substances		

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Screw driver for T10	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove power and fan tray by release screw and pull the latch down then pull out.
2. Remove the screws in cover with screwdriver Phillips #1
3. Remove the screws in bridge board with screwdriver Phillips #1
4. Remove the screws in air baffle with screwdriver Phillips #1 and release cable connector.
5. Remove front panel and tray
6. Remove LED board and button
7. Remove the screws in IF board with screwdriver Phillips #1 and then take out the PCBA.
8. Remove the screws of air baffle in main board and eUSB with screwdriver Phillips #1 and then take out. And remove the battery.
9. Remove the screws in main board with screwdriver Phillips #1 and then take out the PCBA.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

STEP 1.



STEP 2



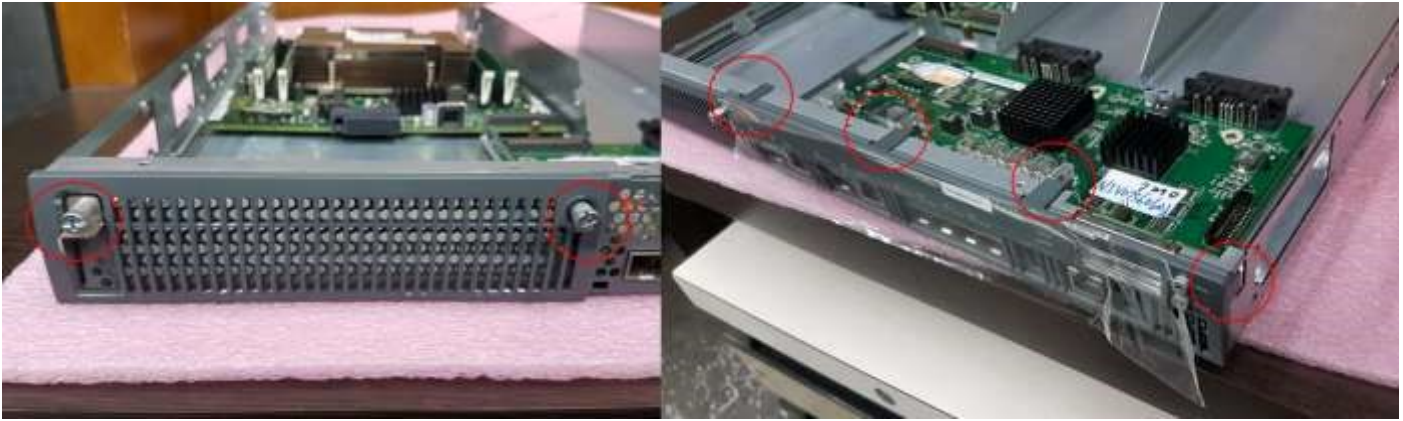
STEP 3



STEP 4



STEP 5



STEP 6



STEP 7



STEP 8



STEP 9

